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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	47
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	52-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21354cdfp-v2

1.2 Product List

Table 1.3 lists Product List for R8C/35C Group, and Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/35C Group.

Table 1.3 Product List for R8C/35C Group

Current of Aug 2010

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F21354CNFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0052JA-A	N version
R5F21355CNFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0052JA-A	
R5F21356CNFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0052JA-A	
R5F21357CNFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0052JA-A	
R5F21358CNFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0052JA-A	
R5F2135ACNFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0052JA-A	
R5F2135CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0052JA-A	
R5F21354CDFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0052JA-A	D version
R5F21355CDFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0052JA-A	
R5F21356CDFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0052JA-A	
R5F21357CDFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0052JA-A	
R5F21358CDFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0052JA-A	
R5F2135ACDFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0052JA-A	
R5F2135CCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0052JA-A	

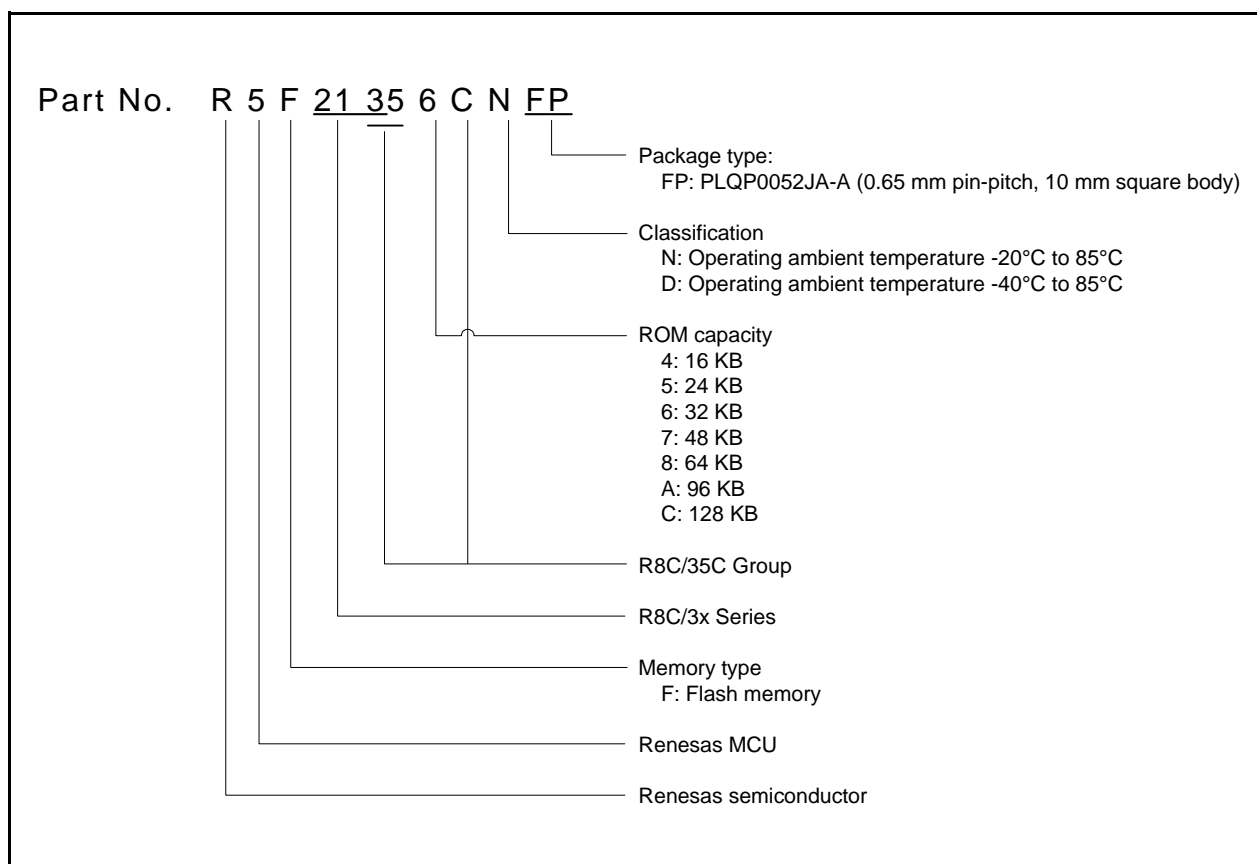


Figure 1.1 Part Number, Memory Size, and Package of R8C/35C Group

Table 1.5 Pin Name Information by Pin Number (2)

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter, Comparator B
36		P1_2	$\overline{KI2}$	(TRCIOB)				AN10
37		P1_1	$\overline{KI1}$	(TRCIOA/TRCTRG)				AN9
38		P1_0	$\overline{KI0}$	(TRCIOD)				AN8
39		P0_7		(TRCIOA)				AN0/DA1
40		P0_6		(TRCIOD)				AN1/DA0
41		P0_5		(TRCIOB)				AN2
42		P0_4		TREO (/TRCIOB)				AN3
43		P0_3		(TRCIOB)	(CLK1)			AN4
44		P0_2		(TRCIOA/TRCTRG)	(RXD1)			AN5
45		P0_1		(TRCIOA/TRCTRG)	(TXD1)			AN6
46		P0_0		(TRCIOA/TRCTRG)				AN7
47		P6_4			(RXD1)			
48		P6_3			(TXD1)			
49		P6_2			(CLK1)			
50		P6_1						
51		P6_0		(TREO)				
52		P5_7						

Note:

1. Can be assigned to the pin in parentheses by a program.

Table 1.7 Pin Functions (2)

Item	Pin Name	I/O Type	Description
Reference voltage input	VREF	I	Reference voltage input pin to A/D converter and D/A converter
A/D converter	AN0 to AN11	I	Analog input pins to A/D converter
	ADTRG	I	A/D external trigger input pin
D/A converter	DA0, DA1	O	D/A converter output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
I/O port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_3 to P4_7, P5_6, P5_7, P6_0 to P6_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. All ports can be used as LED drive ports.
Input port	P4_2	I	Input-only port

I: Input O: Output I/O: Input and output

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

3. Memory

3.1 R8C/35C Group

Figure 3.1 is a Memory Map of R8C/35C Group. The R8C/35C Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 00000h. For example, a 32-Kbyte internal ROM area is allocated addresses 08000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

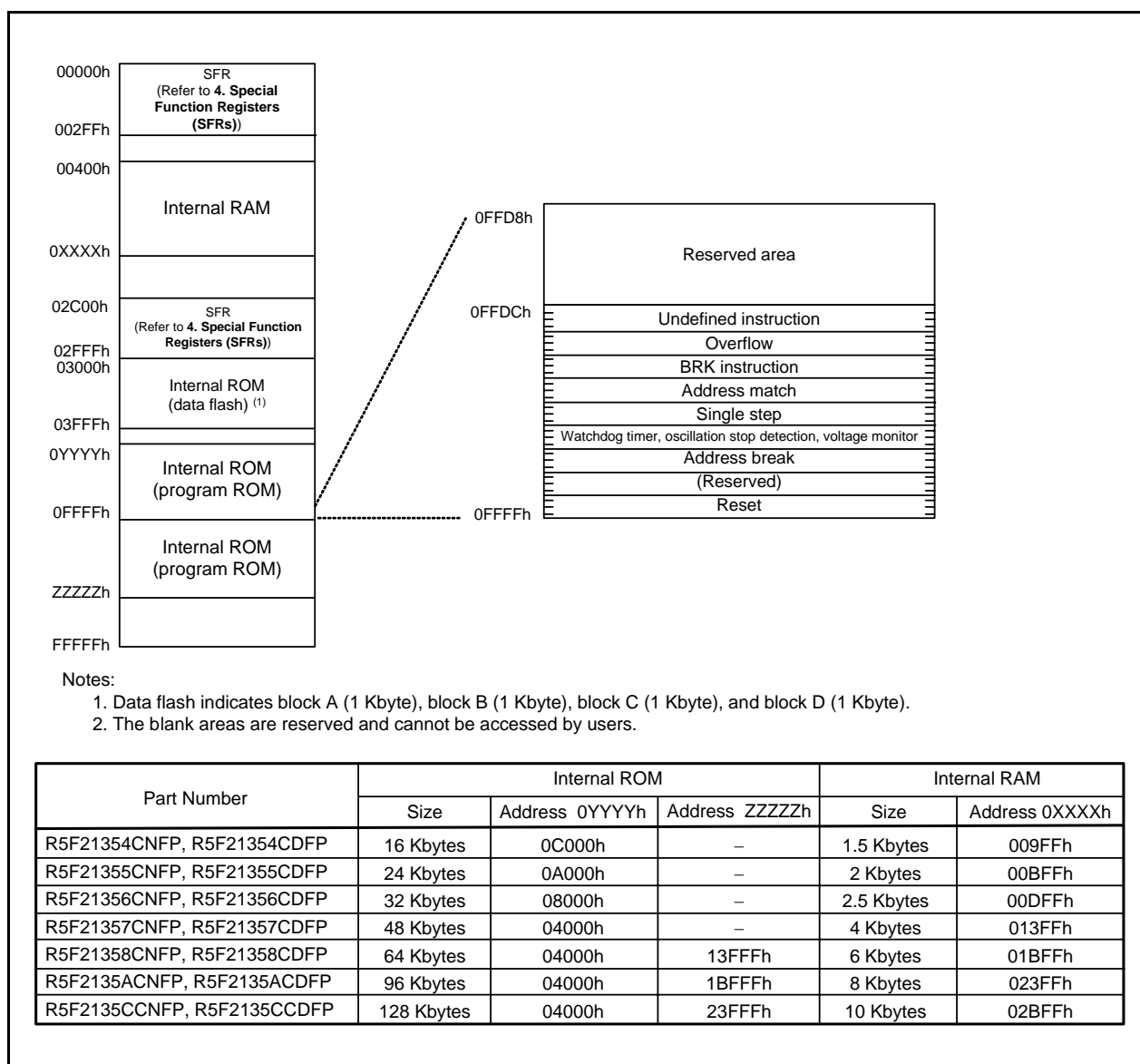


Figure 3.1 Memory Map of R8C/35C Group

Table 4.4 SFR Information (4) (1)

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.6 SFR Information (6) (1)

Address	Register	Symbol	After Reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIOA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIOA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h	UART1 Transmit/Receive Mode Register	U1MR	00h
0161h	UART1 Bit Rate Register	U1BRG	XXh
0162h	UART1 Transmit Buffer Register	U1TB	XXh
0163h			XXh
0164h	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
0165h	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
0166h	UART1 Receive Buffer Register	U1RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.8 SFR Information (8) (1)

Address	Register	Symbol	After Reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h	Address Match Interrupt Enable Register 1	AIER1	00h
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Pull-Up Control Register 0	PUR0	00h
01E1h	Pull-Up Control Register 1	PUR1	00h
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h	Port P1 Drive Capacity Control Register	P1DRR	00h
01F1h	Port P2 Drive Capacity Control Register	P2DRR	00h
01F2h	Drive Capacity Control Register 0	DRR0	00h
01F3h	Drive Capacity Control Register 1	DRR1	00h
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h			
01F8h	Comparator B Control Register 0	INTCMP	00h
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN1	00h
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh	INT Input Filter Select Register 1	INTF1	00h
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After Reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2C8Eh			XXh
2C8Fh			XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
2C9Fh			XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACH			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

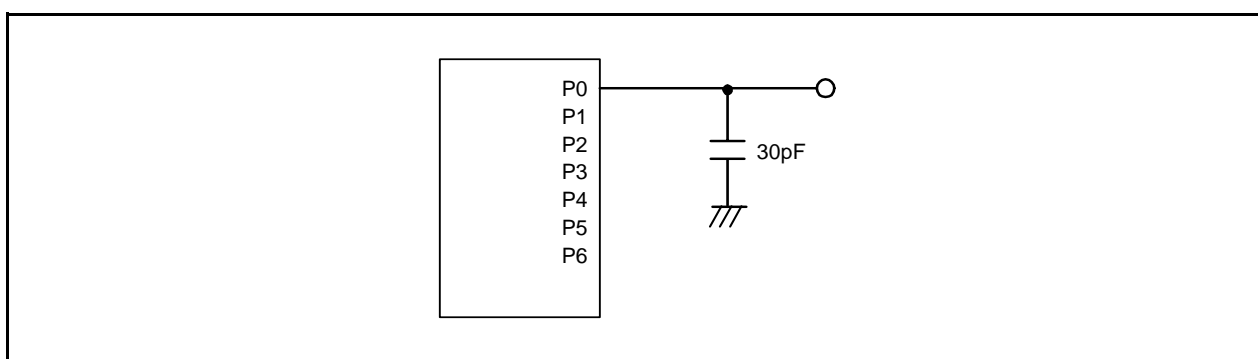


Figure 5.1 Ports P0 to P6 Timing Measurement Circuit

Table 5.4 D/A Converter Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	Resolution		—	—	8	Bit
—	Absolute accuracy		—	—	2.5	LSB
t_{su}	Setup time		—	—	3	μs
R_o	Output resistor		—	6	—	$k\Omega$
I_{Vref}	Reference power input current	(Note 2)	—	—	1.5	mA

Notes:

1. $V_{CC}/AV_{CC} = V_{ref} = 2.7$ to 5.5 V and $T_{opr} = -20$ to $85^{\circ}C$ (N version) / -40 to $85^{\circ}C$ (D version), unless otherwise specified.
2. This applies when one D/A converter is used and the value of the DA_i register ($i = 0$ or 1) for the unused D/A converter is $00h$. The resistor ladder of the A/D converter is not included.

Table 5.5 Comparator B Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{ref}	$IVREF1$, $IVREF3$ input reference voltage		0	—	$V_{CC} - 1.4$	V
V_I	$IVCMP1$, $IVCMP3$ input voltage		-0.3	—	$V_{CC} + 0.3$	V
—	Offset		—	5	100	mV
t_d	Comparator output delay time ⁽²⁾	$V_I = V_{ref} \pm 100$ mV	—	0.1	—	μs
I_{CMP}	Comparator operating current	$V_{CC} = 5.0$ V	—	17.5	—	μA

Notes:

1. $V_{CC} = 2.7$ to 5.5 V, $T_{opr} = -20$ to $85^{\circ}C$ (N version) / -40 to $85^{\circ}C$ (D version), unless otherwise specified.
2. When the digital filter is disabled.

Table 5.6 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance ⁽²⁾		1,000 ⁽³⁾	—	—	times
—	Byte program time		—	80	500	μs
—	Block erase time		—	0.3	—	s
t _d (SR-SUS)	Time delay from suspend request until suspend		—	—	5+CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	μs
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	μs
t _d (CMDRST-READY)	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	—	—	year

Notes:

1. V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.

2. Definition of programming/erasure endurance

The programming and erasure endurance is defined on a per-block basis.

If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.

However, the same address must not be programmed more than once per erase operation (overwriting prohibited).

3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).

4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.

5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.

6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.

7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.10 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet2	Voltage detection level Vdet2_0	At the falling of Vcc	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.10	—	V
—	Voltage detection 2 circuit response time ⁽²⁾	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	μs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

Notes:

1. The measurement condition is Vcc = 1.8 V to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version).
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.11 Power-on Reset Circuit (2)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
trth	External power Vcc rise gradient	⁽¹⁾	0	—	50,000	mV/msec

Notes:

1. The measurement condition is T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.

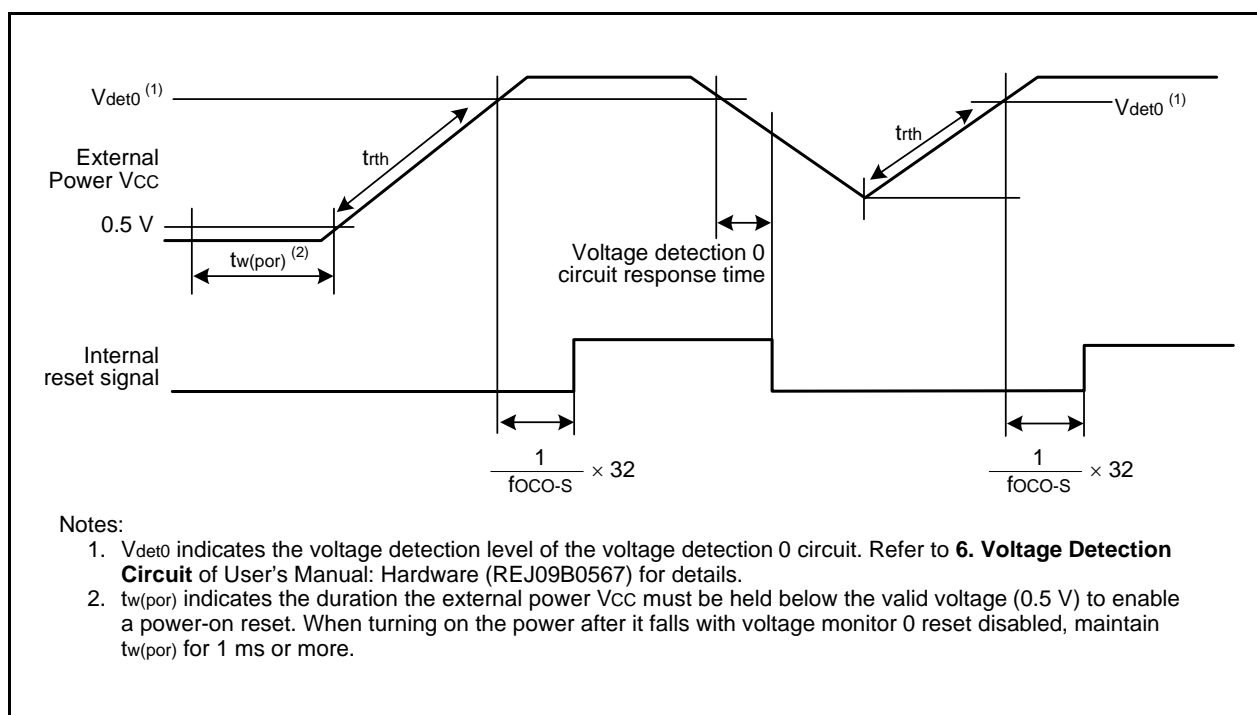
**Figure 5.3 Power-on Reset Circuit Electrical Characteristics**

Table 5.12 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency after reset	$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	38.4	40	41.6	MHz
		$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	38.0	40	42.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register ⁽²⁾	$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	35.389	36.864	38.338	MHz
		$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	35.020	36.864	38.707	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register	$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	30.72	32	33.28	MHz
		$V_{CC} = 1.8 \text{ V to } 5.5 \text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	30.40	32	33.60	MHz
–	Oscillation stability time	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	0.5	3	ms
–	Self power consumption at oscillation	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	400	–	μA

Notes:

1. $V_{CC} = 1.8$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.13 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
–	Oscillation stability time	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	30	100	μs
–	Self power consumption at oscillation	$V_{CC} = 5.0 \text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	2	–	μA

Note:

1. $V_{CC} = 1.8$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.

Table 5.14 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _d (P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		–	–	2,000	μs

Notes:

1. The measurement condition is $V_{CC} = 1.8$ to 5.5 V and $T_{opr} = 25^{\circ}\text{C}$.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

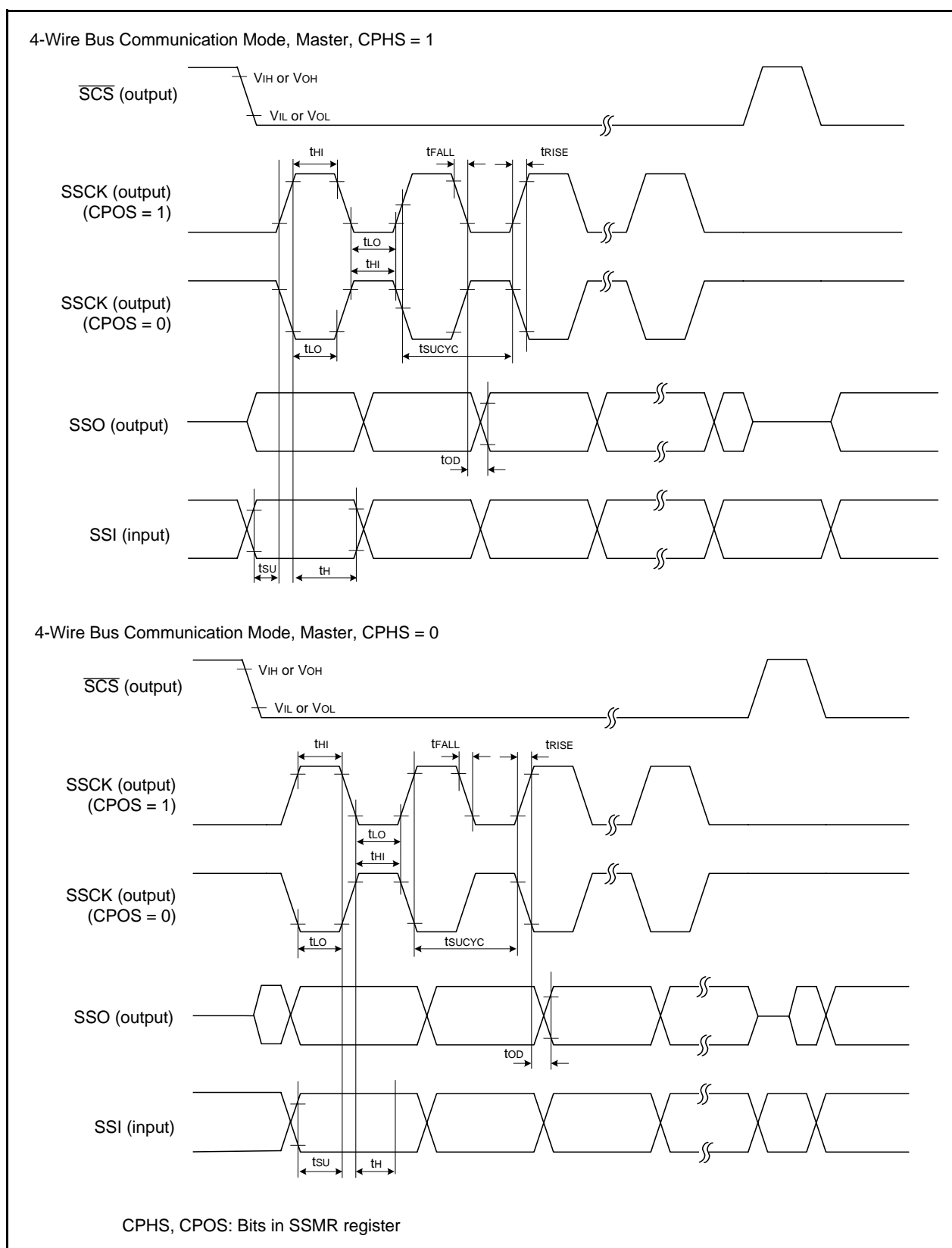


Figure 5.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

Table 5.17 Electrical Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V]

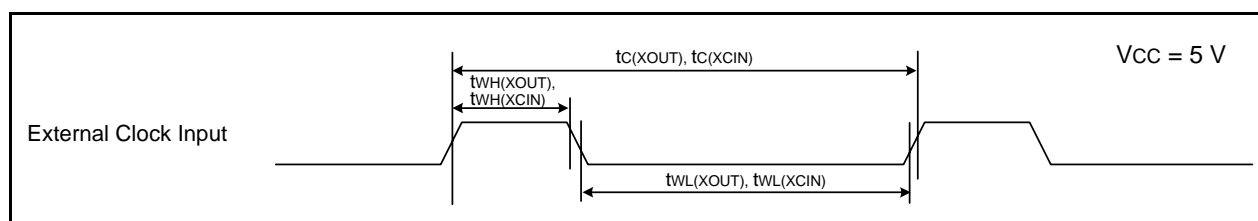
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
VOH	Output "H" voltage	Other than XOUT	Drive capacity High Vcc = 5 V	IOH = -20 mA	Vcc - 2.0	—	Vcc	V
			Drive capacity Low Vcc = 5 V	IOH = -5 mA	Vcc - 2.0	—	Vcc	V
		XOUT	Vcc = 5 V	IOH = -200 μA	1.0	—	Vcc	V
VOL	Output "L" voltage	Other than XOUT	Drive capacity High Vcc = 5 V	IOL = 20 mA	—	—	2.0	V
			Drive capacity Low Vcc = 5 V	IOL = 5 mA	—	—	2.0	V
		XOUT	Vcc = 5 V	IOL = 200 μA	—	—	0.5	V
VT+-VT-	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	—	V
		RESET			0.1	1.2	—	V
IiH	Input "H" current		VI = 5 V, Vcc = 5.0 V		—	—	5.0	μA
IiL	Input "L" current		VI = 0 V, Vcc = 5.0 V		—	—	-5.0	μA
RPULLUP	Pull-up resistance		VI = 0 V, Vcc = 5.0 V		25	50	100	kΩ
RfXIN	Feedback resistance	XIN			—	0.3	—	MΩ
RfXCIN	Feedback resistance	XCIN			—	8	—	MΩ
VRAM	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

1. 4.2 V ≤ Vcc ≤ 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^{\circ}\text{C}$)****Table 5.19 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	24	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	24	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	μs
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	μs
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	μs

**Figure 5.8 External Clock Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.20 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	100	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	40	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	40	—	ns

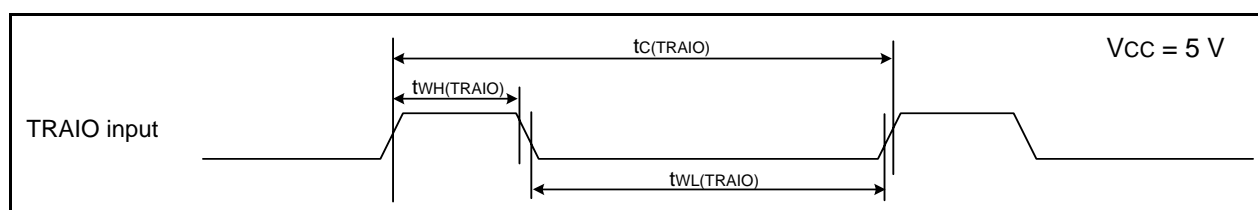
**Figure 5.9 TRAIO Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.29 Electrical Characteristics (5) [$1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High	I _{OH} = -2 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity Low	I _{OH} = -1 mA	V _{CC} - 0.5	—	V _{CC}	V
		XOUT		I _{OH} = -200 μ A	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High	I _{OL} = 2 mA	—	—	0.5	V
			Drive capacity Low	I _{OL} = 1 mA	—	—	0.5	V
		XOUT		I _{OL} = 200 μ A	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.2	—	V
		RESET			0.05	0.20	—	V
I _{IH}	Input "H" current		V _I = 2.2 V, V _{CC} = 2.2 V		—	—	4.0	μ A
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 2.2 V		—	—	-4.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 2.2 V		70	140	300	k Ω
R _{FXIN}	Feedback resistance	XIN			—	0.3	—	M Ω
R _{FXCIN}	Feedback resistance	XCIN			—	8	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

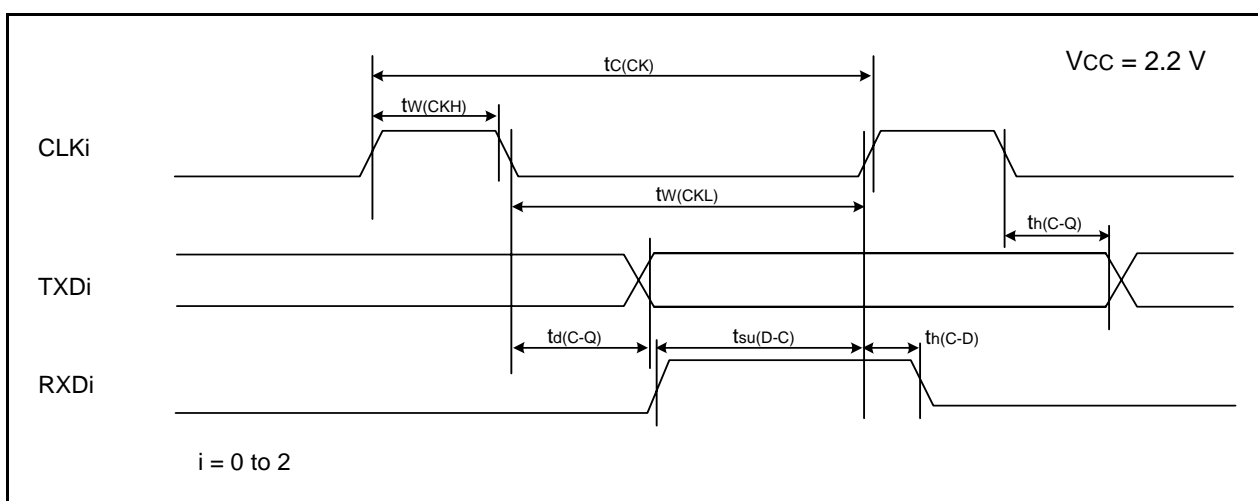
Note:

1. $1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$ and T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 5 MHz, unless otherwise specified.

Table 5.33 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	ns
$t_{w(CKH)}$	CLKi input "H" width	400	—	ns
$t_{w(CKL)}$	CLKi input "L" width	400	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

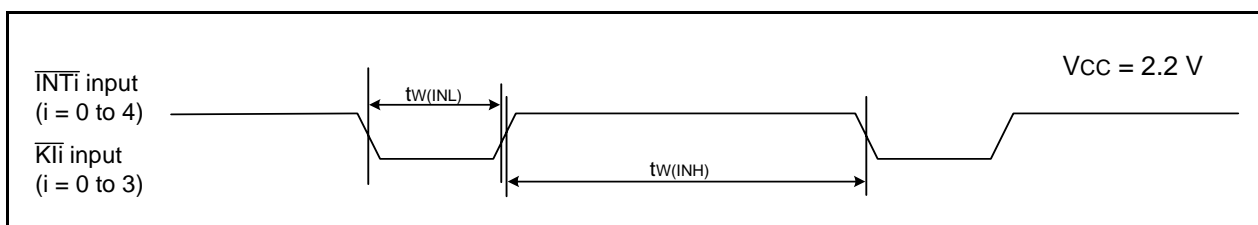
i = 0 to 2

**Figure 5.18 Serial Interface Timing Diagram when Vcc = 2.2 V****Table 5.34 External Interrupt \overline{INTi} (i = 0 to 4) Input, Key Input Interrupt \overline{Kli} (i = 0 to 3)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	\overline{INTi} input "H" width, \overline{Kli} input "H" width	1000 (1)	—	ns
$t_{w(INL)}$	\overline{INTi} input "L" width, \overline{Kli} input "L" width	1000 (2)	—	ns

Notes:

1. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the \overline{INTi} input filter select bit, use an \overline{INTi} input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

**Figure 5.19 Input Timing Diagram for External Interrupt \overline{INTi} and Key Input Interrupt \overline{Kli} when Vcc = 2.2 V**

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